Isolated UART Interface

Auxiliary Power Supply Connector

3.3V LDO for powering the MCU

Isolated UART Interface

+VDC Connector for Powering the Auxiliary Power Supply Board
MSP430F5132 Schematic

Programming Connector for MSP430

Power Supply Supervisor for MCU

Speed Reference through Potentiometer

DC Bus & Winding Voltage Sense Feedback

ESD Protection for Voltage Sensing

Temperature Sensor
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Project Title: 230V, 250W, Mains Powered BLDC Motor Drive

Designed for: Public Release

Sheet Title:

Size:

Mod. Date:

File:

Sheet:

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Version control disabled

SVN Rev: TIDA-00472

Number: Rev: E1

Label Table

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<th>Variant</th>
<th>Label Text</th>
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<td>ChangeMe!</td>
</tr>
<tr>
<td>002</td>
<td>ChangeMe!</td>
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ZS1

assembly/NOTE

The Assembly note is for PCB labels only

ZS2

assembly/NOTE

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZS3

assembly/NOTE

These assemblies must be clean and free from flux and all contaminants. Use of no-clean flux is not acceptable.

ZS4

assembly/NOTE

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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